

FIGURE 1

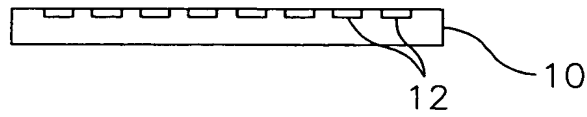


FIGURE 2A

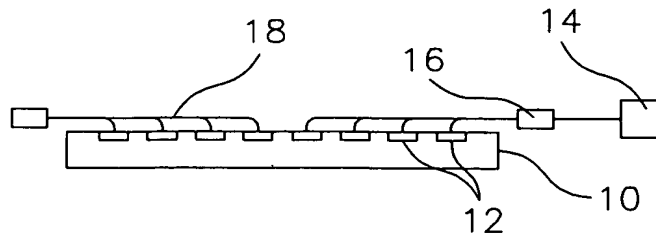


FIGURE 2B

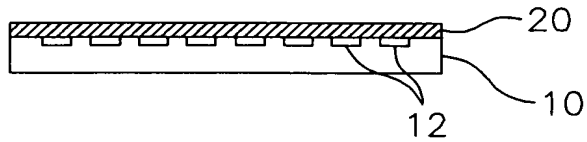


FIGURE 2C

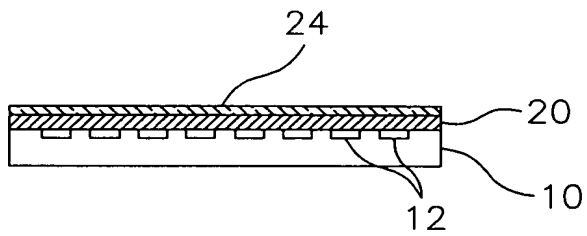


FIGURE 2D

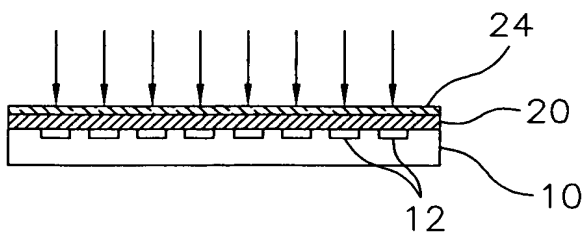


FIGURE 2E

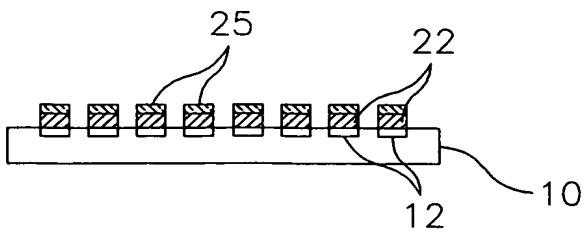


FIGURE 2F

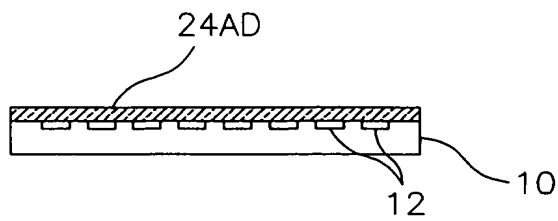


FIGURE 2G

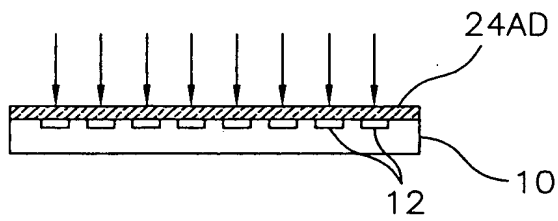


FIGURE 2H

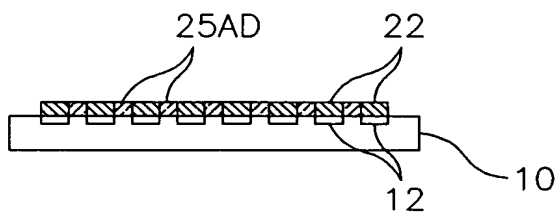


FIGURE 2I

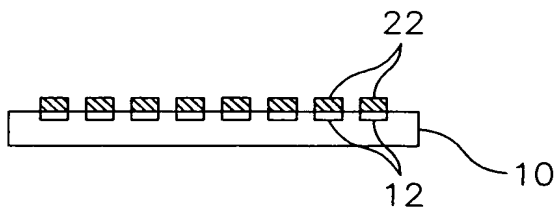


FIGURE 2J

FIG. 2G is a cross-sectional view of a device in accordance with the present invention. The device includes a substrate 10 having a series of features 12 on its top surface. A layer 24AD is deposited over the features 12. FIG. 2H is a cross-sectional view of the device after the layer 24AD has been deposited over the features 12. Arrows point down to the features 12, indicating they are still visible beneath the layer 24AD. FIG. 2I is a cross-sectional view of the device after a layer 25AD has been deposited over the layer 24AD. The features 12 are still visible beneath the layers. A label 22 points to the top surface of the layer 25AD. FIG. 2J is a cross-sectional view of the device after the features 12 are completely covered by the layers 24AD and 25AD. The label 22 points to the top surface of the layer 25AD.

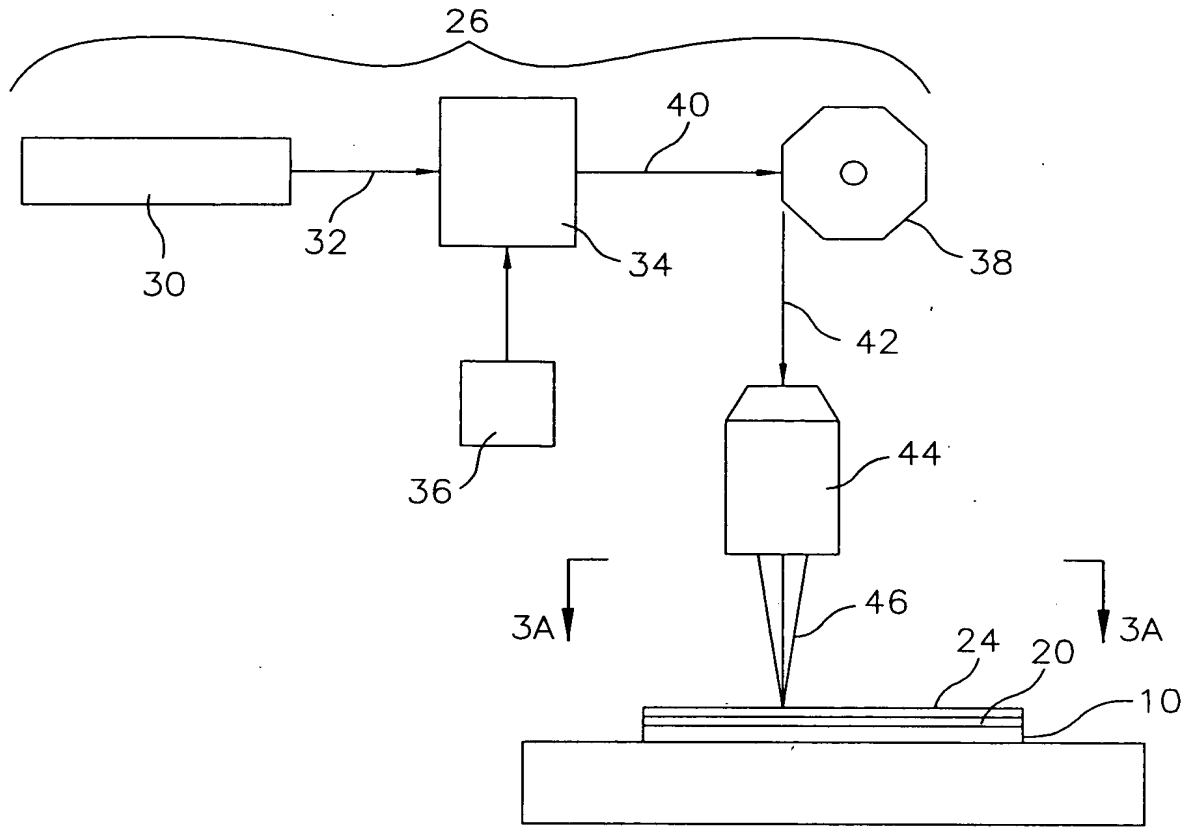


FIGURE 3

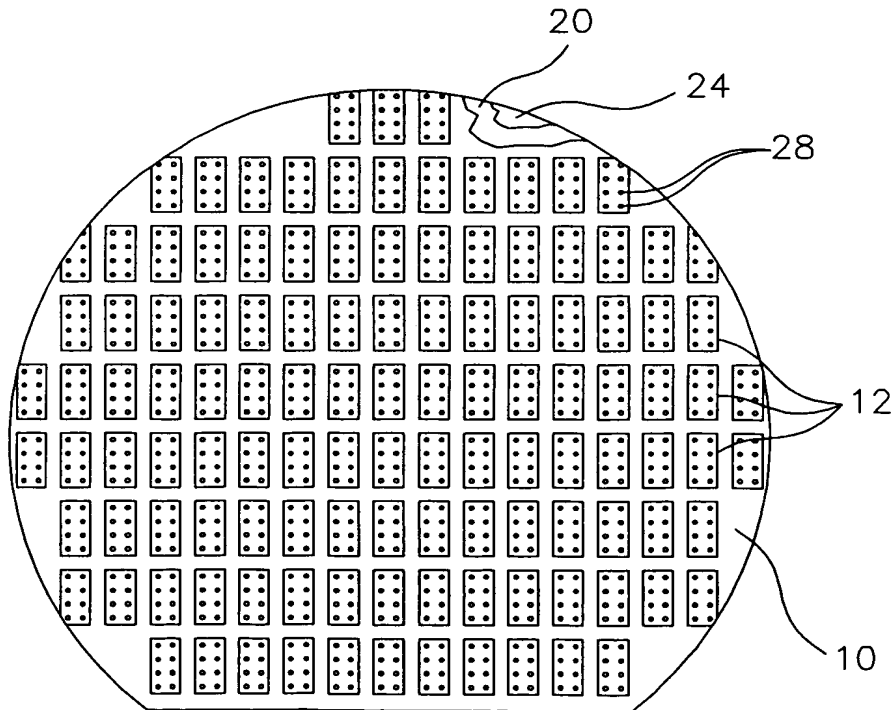


FIGURE 3A

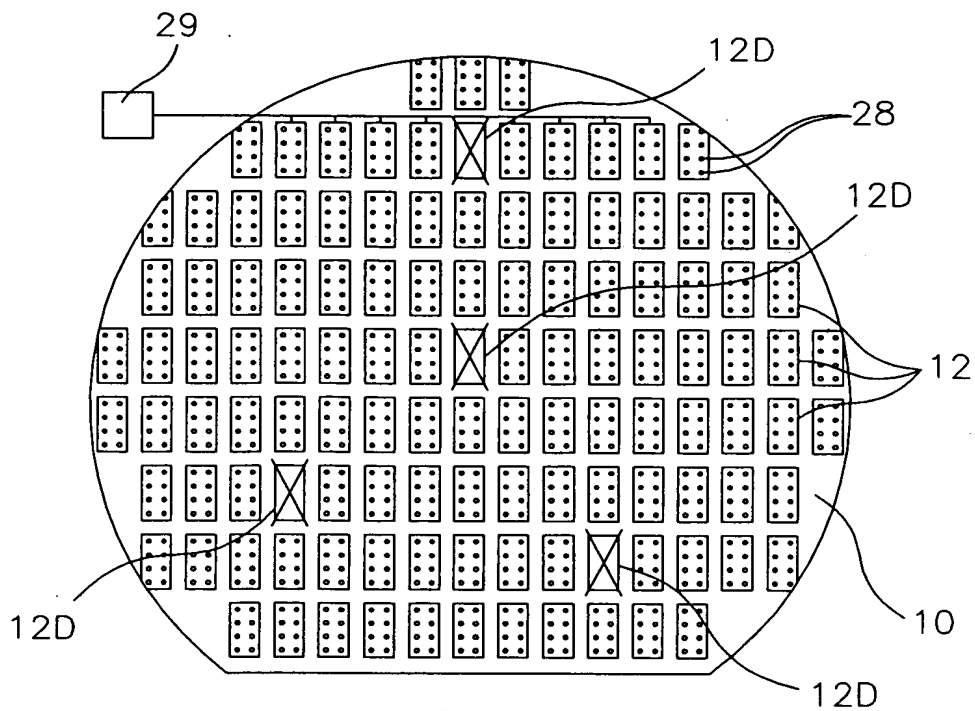


FIGURE 4

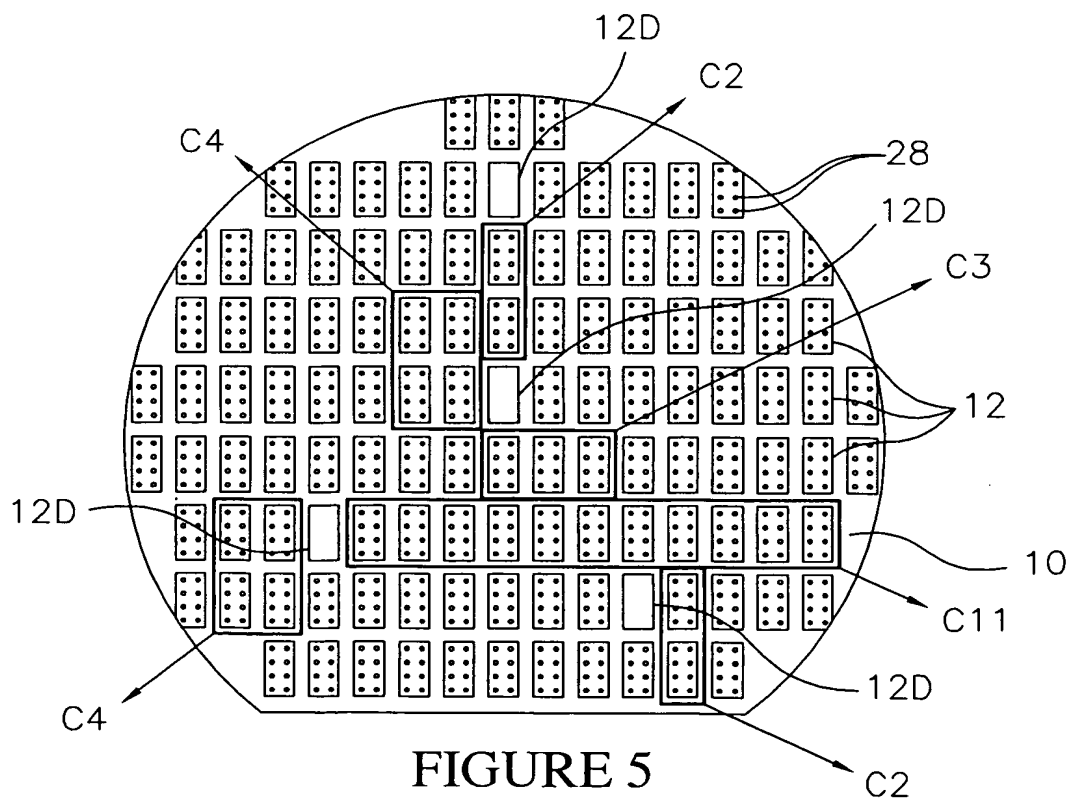


FIGURE 5

